



Recommended PCB Layout THK=1.2mm

TOLERANCE=±0.05

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: 铜合金.
- 1.3 CONTACT 5~9PIN: 铜合金.
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

- 2.1 CONTACT:  
CONTACT AREA: GOLD PLATING.  
SOLDER AREA: 100u" Min MATTE TIN PLATING.  
UNDER PLATE: 50u" Min NICKEL PLATING.
- 2.2 SHELL: 50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

- 3.1 ELECTRICAL CHARACTERISTICS:  
CONTACT RESISTANCE: 30mΩ MAXIMUM  
CONTACT CURRENT RATING: 3A  
DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.  
INSULATION RESISTANCE: 1000 MEGOHMS MIN  
OPERATING TEMPERATURE: -25~C ~ +85° C

3.2 MECHANICAL:

Before lifespan: insertion force 8-25N;  
pull-out force 10-25N.

After lifespan: 6N Min.

4. PART MUST COMPLY ROHS SPECIFICATION

5. SOLDER RESISTANCE TEMPERATURE:

260 ± 5° C FOR 3 MINUTES.

3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	铜合金	Overall nickel plating 50u" ~ 100u", contact area gold plating 1U", welding leg tin plating 100u"
1	HSG	LCP+30%GF	Black UL94V-0
NO.	PART NAME	MATERIAL	DESCRIPTION



深圳市华宇创精密电子有限公司

<b>TOLERANCE:</b> X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5'	<b>DRAWN BY :</b> 陈一鸣	<b>DATE :</b> 2014-02-23	<b>PART NAME:</b> USB 3.0 AF 板上DIP H=5.4 CH2.7 无卷边	
	<b>CHECKED BY:</b> 马跃	<b>DATE :</b> 2014-02-23	<b>PART NO.</b> HYC182-USBA09-540	<b>MOLD NO.</b> /
UNIT: mm [inch] SCALE:1:1 SIZE: A4	<b>APPROVED BY:</b> 邱敏	<b>DATE :</b> 2014-02-23	<b>DRAW NO:</b> HYC-2604281516	<b>SHEET NO.</b> 1 OF 1